



TC-TAP-2-HP Series

Shin-Etsu Silicones of America, Inc.
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Product Features

- High thermal conductivity
- High heat resistance
- 0.23mm thickness available
- Excellent electrical properties
- Superior strength and hardness

Typical Applications

- Vehicle inverters/converters
- Power Transistors
- Power Modules
- LED Modules

Typical Properties

Type	High Hardness Thermal Pads
Low Molecular Weight Siloxane Stripped?	Y
Density @ 23C (g/cm ³)	2.70
Shore A Hardness	90
Tensile Strength (MPa)	17.00
Dielectric Strength (kV/mm)	48.0
Thermal Conductivity (W/m·K)	1.80
Thermal Resistance (mm ² ·K/W)	270
Usable Temp. Range (C)	-40 to +250
Thickness (mm)	0.23
Reinforced Layer	Polyimide
Sheet Size (mm)	200 x 300

Note: Values are not for specification purposes.

Physical properties are typical for the thickness given. Other thicknesses may have slightly varying properties and are available upon request.

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